

NPN Silicon Power Darlington Transistors

MJB5742T4G

The Darlington transistors are designed for high-voltage power switching in inductive circuits.

Features

• These Devices are Pb-Free and are RoHS Compliant

Applications

- Small Engine Ignition
- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Motor Controls

MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V _{CEO(sus)}	Collector-Emitter Voltage	400	Vdc
V _{CEV}	Collector-Emitter Voltage	800	Vdc
V _{EB}	Emitter-Base Voltage	8	Vdc
I _C	Collector Current – Continuous – Peak (Note 1)	8 16	Adc
I _B I _{BM}	Base Current – Continuous – Peak (Note 1)	2.5 5	Adc
P _D	Total Device Dissipation @ T _A = 25°C Derate above 25°C	2 0.016	W W/°C
P _D	Total Device Dissipation @ T _C = 25°C Derate above 25°C	100 0.8	W W/°C
T _J , T _{stg}	Operating and Storage Junction Temperature Range	-65 to +150	°C

THERMAL CHARACTERISTICS

Symbol	Characteristics	Max	Unit
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case	1.25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	°C/W
TL	Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 5 Seconds	275	°C

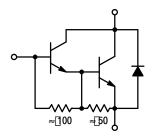
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

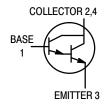
1

1. Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.

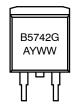
POWER DARLINGTON TRANSISTORS 8 AMPERES, 400 VOLTS 100 WATTS







MARKING DIAGRAM



B5742 = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MJB5742T4G	D ² PAK (Pb-Free)	800 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MJB5742T4G

Symbol	Characteristic	Min	Тур	Max	Unit
OFF CHARA	CTERISTICS (Note 2)				
V _{CEO(sus)}	Collector-Emitter Sustaining Voltage (I _C = 50 mA, I _B = 0)	400	-	-	Vdc
I _{CEV}	Collector Cutoff Current (V _{CEV} = Rated Value, V _{BE(off)} = 1.5 Vdc) (V _{CEV} = Rated Value, V _{BE(off)} = 1.5 Vdc, T _C = 100°C)	- -	- -	1 5	mAdc
I _{EBO}	Emitter Cutoff Current (V _{EB} = 8 Vdc, I _C = 0)	-	_	75	mAdc
SECOND BR	EAKDOWN				
I _{S/b}	Second Breakdown Collector Current with Base Forward Biased	See Figure 6			
RBSOA	Clamped Inductive SOA with Base Reverse Biased	See Figure 7			
ON CHARAC	TERISTICS (Note 2)				
h _{FE}	DC Current Gain ($I_C = 0.5$ Adc, $V_{CE} = 5$ Vdc) ($I_C = 4$ Adc, $V_{CE} = 5$ Vdc)	50 200	100 400	- -	-
V _{CE(sat)}	Collector–Emitter Saturation Voltage (I_C = 4 Adc, I_B = 0.2 Adc) (I_C = 8 Adc, I_B = 0.4 Adc) (I_C = 4 Adc, I_B = 0.2 Adc, I_C = 100°C)		- - -	2 3 2.2	Vdc
V _{BE(sat)}	Base–Emitter Saturation Voltage (I_C = 4 Adc, I_B = 0.2 Adc) (I_C = 8 Adc, I_B = 0.4 Adc) (I_C = 4 Adc, I_B = 0.2 Adc, I_C = 100°C)	- - -	- - -	2.5 3.5 2.4	Vdc
V _f	Diode Forward Voltage (Note 3) (I _F = 5 Adc)	-	_	2.5	Vdc

SWITCHING CHARACTERISTICS

Typical Re	Typical Resistive Load (Table 1)							
t _d	Delay Time		_	0.04	_	μs		
t _r	Rise Time	(V _{CC} = 250 Vdc, I _{C(pk)} = 6 A	_	0.5	-	μs		
t _s	Storage Time	$I_{B1} = I_{B2} = 0.25 \text{ A, } t_p = 25 \text{ μs,}$ Duty Cycle $\leq 1\%$)	_	8	-	μs		
t _f	Fall Time]	-	2	-	μs		
Inductive	Inductive Load, Clamped (Table 1)							
t _{sv}	Voltage Storage Time	(I _{C(pk)} = 6 A, V _{CE(pk)} = 250 Vdc	_	4	-	μs		
t _c	Crossover Time	$(I_{C(pk)} = 6 \text{ A}, V_{CE(pk)} = 250 \text{ Vdc}$ $I_{B1} = 0.06 \text{ A}, V_{BE(off)} = 5 \text{ Vdc})$	_	2	-	μs		

Pulse Test: Pulse Width 300 μs, Duty Cycle = 2%.
 The internal Collector–to–Emitter diode can eliminate the need for an external diode to clamp inductive loads. Tests have shown that the Forward Recovery Voltage (V_f) of this diode is comparable to that of typical fast recovery rectifiers.

MJB5742T4G

TYPICAL CHARACTERISTICS

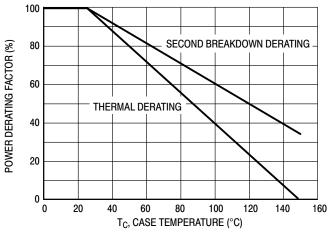


Figure 1. Power Derating

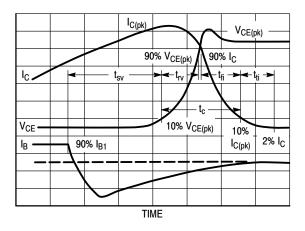


Figure 2. Inductive Switching Measurements

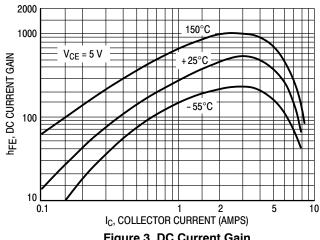


Figure 3. DC Current Gain

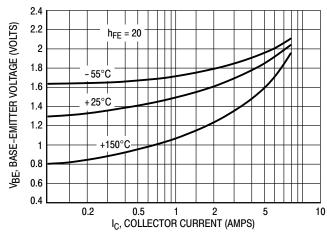


Figure 4. Base-Emitter Voltage

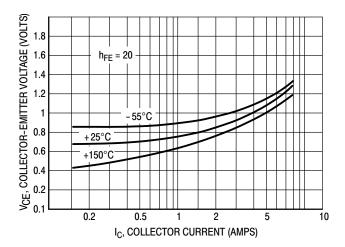
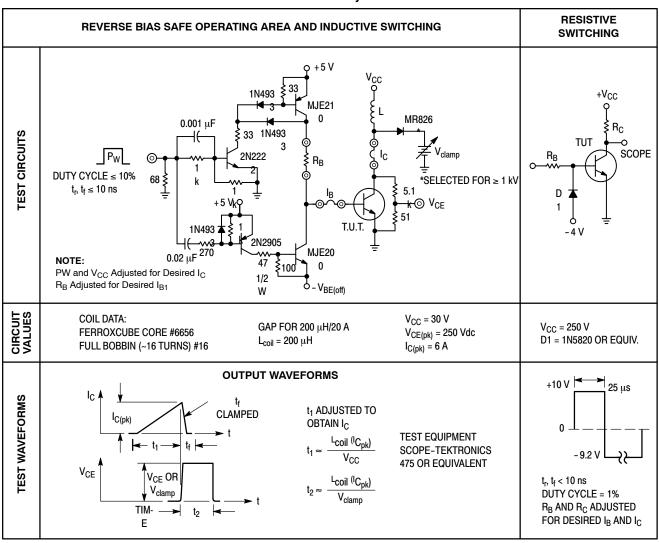


Figure 5. Collector-Emitter Saturation Voltage

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Table 1. Test Conditions for Dynamic Performance



SAFE OPERATING AREA INFORMATION

FORWARD BIAS

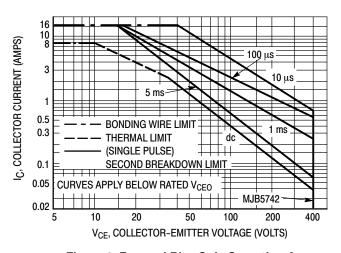
There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C – V_{CE} limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on $T_C = 25^{\circ}C$; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \ge 25^{\circ}C$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 6 may be found at any case temperature by using the appropriate curve on Figure 1.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current condition allowable during reverse biased turnoff. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 7 gives the complete RBSOA characteristics.

The Safe Operating Area figures shown in Figures 6 and 7 are specified ratings for these devices under the test conditions shown.



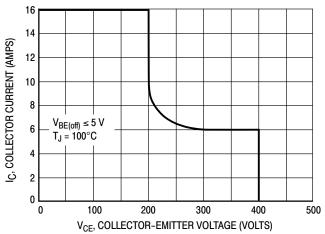


Figure 6. Forward Bias Safe Operating Area

Figure 7. Reverse Bias Safe Operating Area

RESISTIVE SWITCHING PERFORMANCE

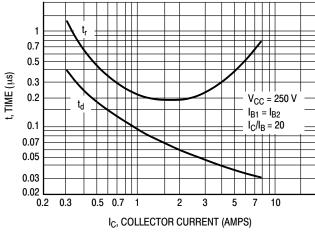


Figure 8. Turn-On Time

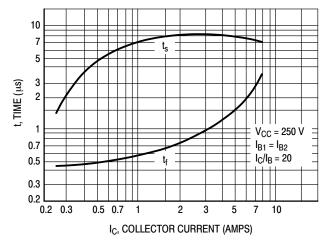


Figure 9. Turn-Off Time

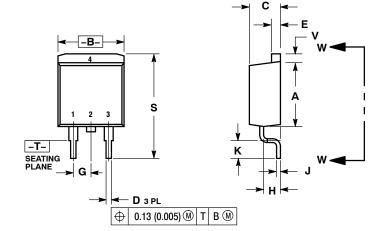




D²PAK 3 CASE 418B-04 **ISSUE L**

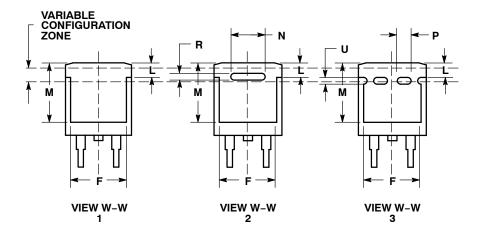
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SCALE 1:1



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- 3. 418B-01 THRU 418B-03 OBSOLETE,
- NEW STANDARD 418B-04.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100	BSC	2.54 BSC	
Н	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



STYLE 1: PIN 1. BASE 2. COLLECTOR
3. EMITTER
4. COLLECTOR STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

STYLE 4:

PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

STYLE 6: PIN 1. NO CONNECT 2. CATHODE 3. ANODE 4. CATHODE

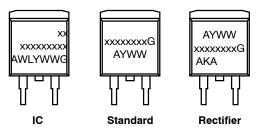
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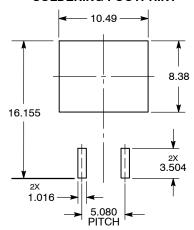
GENERIC MARKING DIAGRAM*



xx = Specific Device Code A = Assembly Location

WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package
AKA = Polarity Indicator

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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